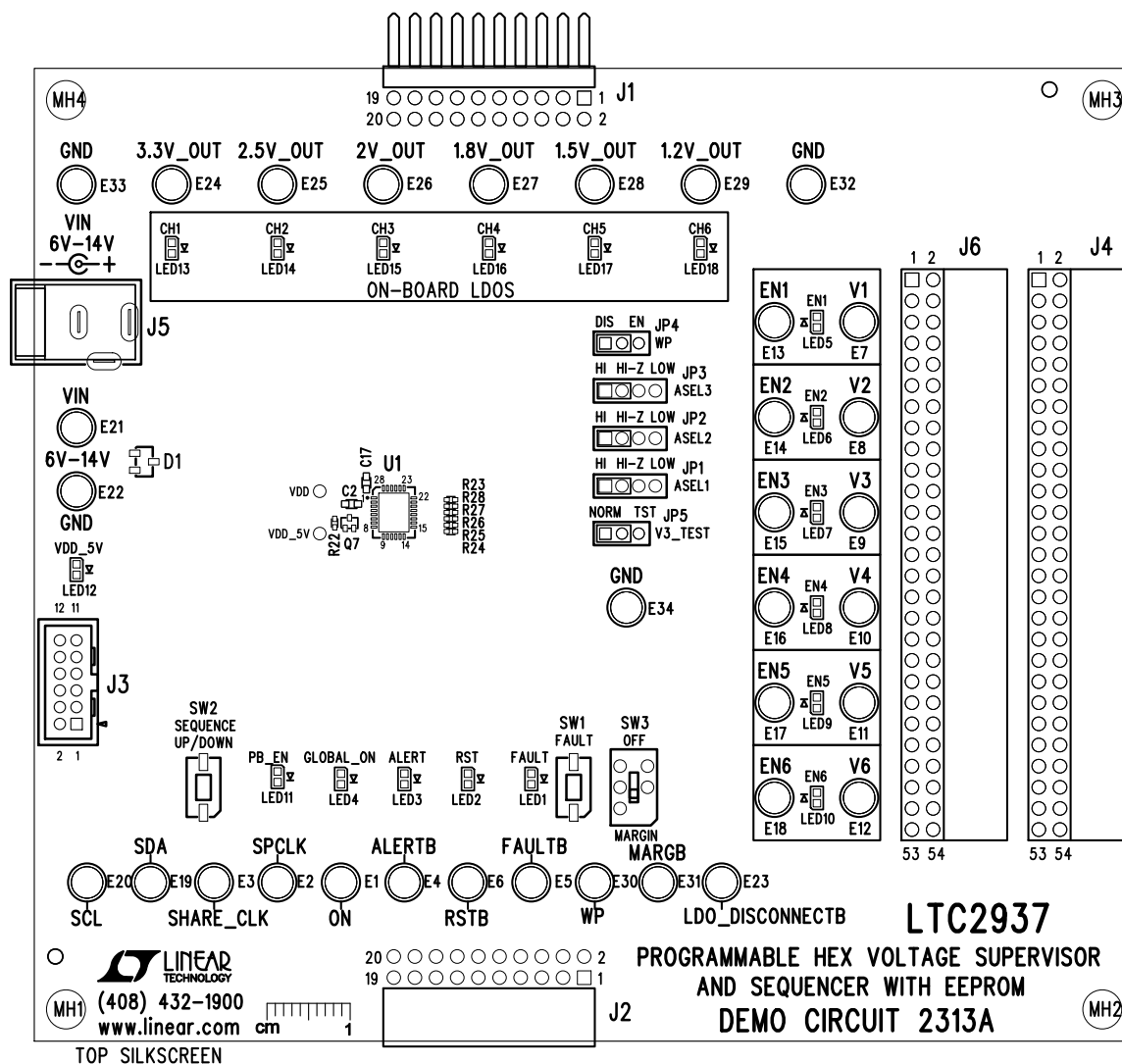
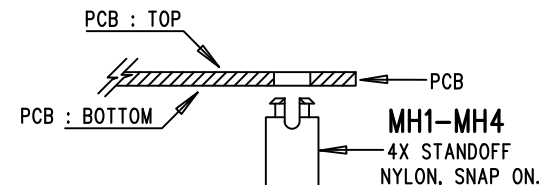



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	3	3RD PROTOTYPE	NATHAN E.	03-24-15

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN BELOW:



APPROVALS			
PCB DES.	KIM T.		
APP ENG.	NATHAN E.	<b>TITLE: TOP ASSEMBLY DRAWING</b> <b>PROGRAMMABLE HEX VOLTAGE SUPERVISOR</b> <b>AND SEQUENCER WITH EEPROM</b>	
		SIZE	IC NO. LTC2937IUHE
		N/A	DEMO CIRCUIT 2313A
SCALE = NONE		REV.	3
		FILENAME:	DC2313A-3.PCB
		SHT	1 OF 2

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